

SCMM1206S1 Series, Current Sensor Resistor (Lead / Halogen Free)

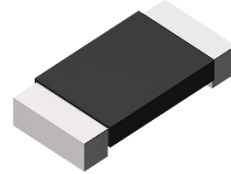
The history of revision change for the specification

| Date | Revision | Changes |
|------------|----------|---|
| 2021/11/30 | A0 | New Approval standard (POYIN) |
| 2021/12/15 | A1 | Modify life condition: Terminal temperature 70°C (POYIN) |
| 2022/2/17 | A2 | Terminal temperature of power derating figure and description are replaced with ambient temperature Modify life condition as 70°C , 100% rated power (POYIN) |
| 2022/3/9 | A3 | Add resistance 2/3/4/7/9 and modify solder pad figure (POYIN) |
| 2022/7/11 | A4 | (1) Modify package and carrier picture in P.6 (CH) (2) Add 2 descriptions in Care note for storage of Care Note chapter (CH) |
| 2023/2/23 | A5 | Remove ESD test item (CH) |

SCMM1206S1 Series, Current Sensor Resistor (Lead / Halogen Free)

Features / Applications :

- High power rating is up to 1W
- Welding construction; excellent long-term stability
- Industrial applications & Current Sensor Resistor
- RoHS compliant



Electrical Specifications :

| Characteristics ¹ | Feature |
|--|---------------------|
| Power Rating ² | 1W |
| Resistance Value | 1 to 10 mΩ |
| Temperature Coefficient of Resistance (25/125°C) | ±75 ppm/°C |
| Operation Temperature Range | -65°C ~ +170°C |
| Resistance Tolerance | ±1 % |
| Maximum Working Voltage (V) | $(P \cdot R)^{1/2}$ |

1. For detail information refer to the table on page 3 P/N list
2. For resistors are operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

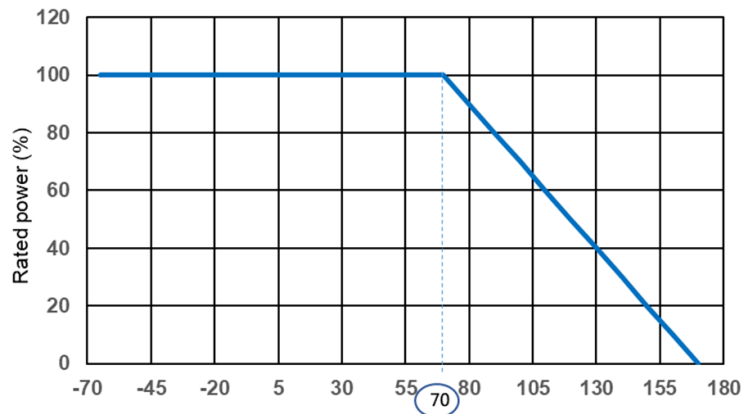
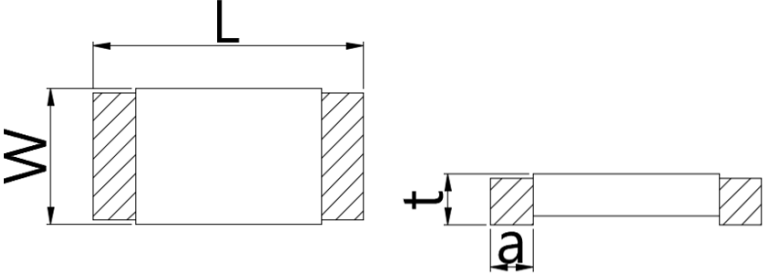


Figure 1. : Power derating curve at ambient temperature

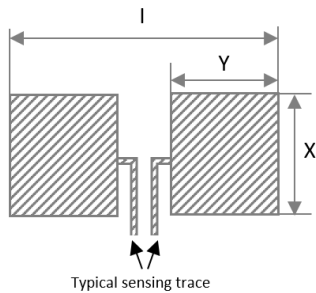
Outline Drawing :

Construction and Dimension



| Dimensions (mm) | | | |
|--------------------------|-----------------|-----------------|----------------|
| Resistance Range (mΩ) | 1 | 2, 3, 4, 5 | 6, 7, 8, 9, 10 |
| L | 3.20 ± 0.25 | | |
| W | 1.60 ± 0.25 | | |
| t | 0.60 ± 0.25 | | |
| a | 1.0 ± 0.25 | 0.65 ± 0.25 | 0.5 ± 0.25 |

Recommended Solder Pad Dimensions



| Resistance Range | Dimensions | | |
|------------------|------------|--------|--------|
| mΩ | X (mm) | Y (mm) | I (mm) |
| 1 to 10 | 1.8 | 1.6 | 4.0 |

Type Designation :

S C M M 1206 S □ — □□□□ □
 (1) (2) (3) (4) (5) (6)

Note :

- (1) Series No.
- (2) Size
- (3) Terminal Type : S = Short terminal
- (4) Power Rating : 1 = 1W
- (5) Resistance Value : R001 = 0.001Ω
- (6) Tolerance : F = ±1%, G = ±2%, J = ±5%

P/N list :

| P/N | R value | TCR | Power Rating | Tolerance | | |
|------------------|---------|---------|--------------|-----------|----|----|
| | (mΩ) | (ppm/K) | (W) | 1% | 2% | 5% |
| SCMM1206S1-R001* | 1.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R002* | 2.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R003* | 3.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R004* | 4.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R005* | 5.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R006* | 6.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R007* | 7.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R008* | 8.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R009* | 9.0 | ±75 | 1 | ✓ | | |
| SCMM1206S1-R010* | 10.0 | ±75 | 1 | ✓ | | |

* Note : Other values and tolerance would be available, please contact Cyntec.

Characteristics :

Electrical

| Item | Specification and Requirement | Test Method |
|-------------------------------|---|---|
| Temperature Coefficient (TCR) | As follow specification | JIS-C-5201 +25°C / +125°C |
| Short Time Overload | $\Delta R: \pm 0.5\%$ Without damage by flashover, spark, arcing, burning or breakdown | JIS-C-5201-1 4.13 2.5 x rated power for 5 seconds |
| Insulation Resistance | Over 100 M Ω on overcoat layer face up | JIS-C-5201-1 4.6 100V _{DC} for 60 +10/-0 seconds |
| Voltage Proof | $\Delta R: \pm 1.0\%$ Without damage by flashover, spark, arcing, burning or breakdown | JIS-C-5201-1 4.7 400V _{AC(rms.)} for 60 +10/ -0 seconds |

Mechanical

| Item | Specification and Requirement | Test Method |
|---------------------------|---|--|
| Solderability | The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder | J-STD-002 Method B category 3 245 \pm 5°C for 5 \pm 0.5 seconds |
| Resistance to Solder Heat | $\Delta R: \pm 0.5\%$ Without distinct damage in appearance | MIL-STD-202 Method 210 260 \pm 5°C for 10 \pm 1 seconds |
| Board Flex | $\Delta R: \pm 1.0\%$ Without mechanical damage such as break | AEC-Q200-005 Bending value: 2 mm for 60 \pm 1 seconds |
| Vibration | $\Delta R: \pm 0.5\%$ Without distinct damage in appearance | MIL-STD-202 Method 204 5G's for 20 minutes, 12 cycles each of 3 orientations Test from 10-2000Hz |

| | | |
|----------------------------|--|--|
| Mechanical Shock | $\Delta R: \pm 0.5\%$ Without distinct damage in appearance | MIL-STD-202 Method 213 100G's peak value, 6ms, half-sine waveform, 12.3 ft/sec |
| Terminal Strength (SMD) | $\Delta R: \pm 1.0\%$ Without mechanical damage such as break | AEC-Q200-006 Force of 1.8Kg for 60 seconds |

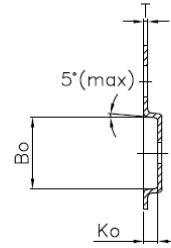
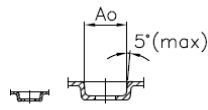
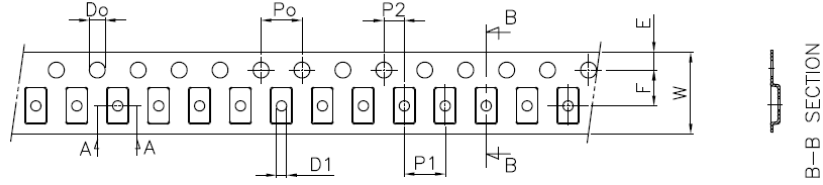
Endurance

| Item | Specification and Requirement | Test Method |
|-----------------------------|--|---|
| Temperature Cycling | $\Delta R: \pm 0.5\%$ Without distinct damage in appearance | JESD22 Method JA-104 -55°C to 150°C /1000cycle 30 minutes maximum dwell time at each temperature |
| Biased Humidity | $\Delta R: \pm 0.5\%$ Without distinct damage in appearance | MIL-STD-202 Method 103 1000 hours, 85°C /85% RH, applied for 10% rated power |
| Operational Life | $\Delta R: \pm 1.0\%$ Without distinct damage in appearance | MIL-STD-202 Method 108 70°C, 100% rated power 1.5 hours ON, 0.5 hours Off For total 1000 hours |
| High Temperature Storage | $\Delta R: \pm 1.0\%$ Without distinct damage in appearance | MIL-STD-202 Method 108 170°C for 1000 hours |
| Moisture Resistance | $\Delta R: \pm 0.5\%$ Without distinct damage in appearance | MIL-STD-202 Method 106 65°C /90-100% RH, unpowered, 7b not required |

Note : Measurement at 24 ± 4 hours after test conclusion for all reliability tests-parts.

PACKAGING DESCRIPTIONS :

Dimensions :

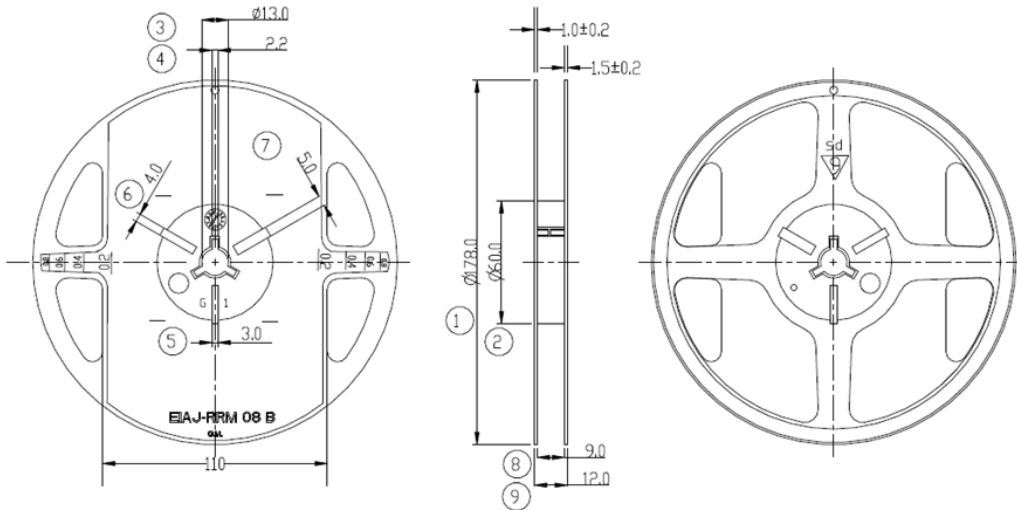


A-A SECTION

Unit:mm

| | | | | | |
|----|-------------|----|-------------|----|--------------|
| A0 | 2.00 ± 0.10 | P2 | 2.00 ± 0.05 | D1 | 1.05 ± 0.05 |
| B0 | 3.50 ± 0.10 | T | 0.20 ± 0.10 | W | 8.00 ± 0.30 |
| K0 | 0.75 ± 0.10 | E | 1.75 ± 0.10 | P0 | 40.00 ± 0.20 |
| P0 | 4.00 ± 0.10 | F | 3.50 ± 0.05 | K1 | 1.50(MAX) |
| P1 | 4.00 ± 0.10 | D0 | 1.55 ± 0.05 | | |

Reel Dimensions :

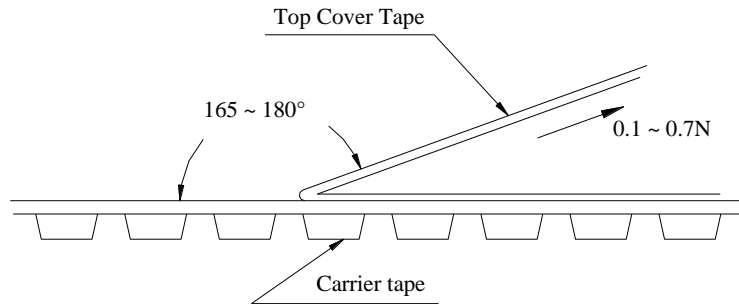


Unit:mm

| Symbol | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 |
|--------|-------------|-----------------|--------------|-------------|----------------|----------------|----------------|-------------|---------------|
| Size | 178.0 ±1 | 60.0 +0.5/-0 | 13.0 ±0.2 | 2.2 ±0.5 | 3.0 +0.5/-0 | 4.0 +0.5/-0 | 5.0 +0.5/-0 | 9.0 ±0.5 | 12.0 ±0.15 |

Peel Strength of Top Cover Tape :

The peel speed shall be about 300 mm/min and the peel force of top cover tape shall between 0.1 to 0.7N



Number of Taping :

4,000 pieces / reel

Label Marking :

The following items shall be marked on tray

- (1) Description
- (2) Quantity
- (3) Part No.
- (4) Tapping No.

Care Note :

Care note for storage

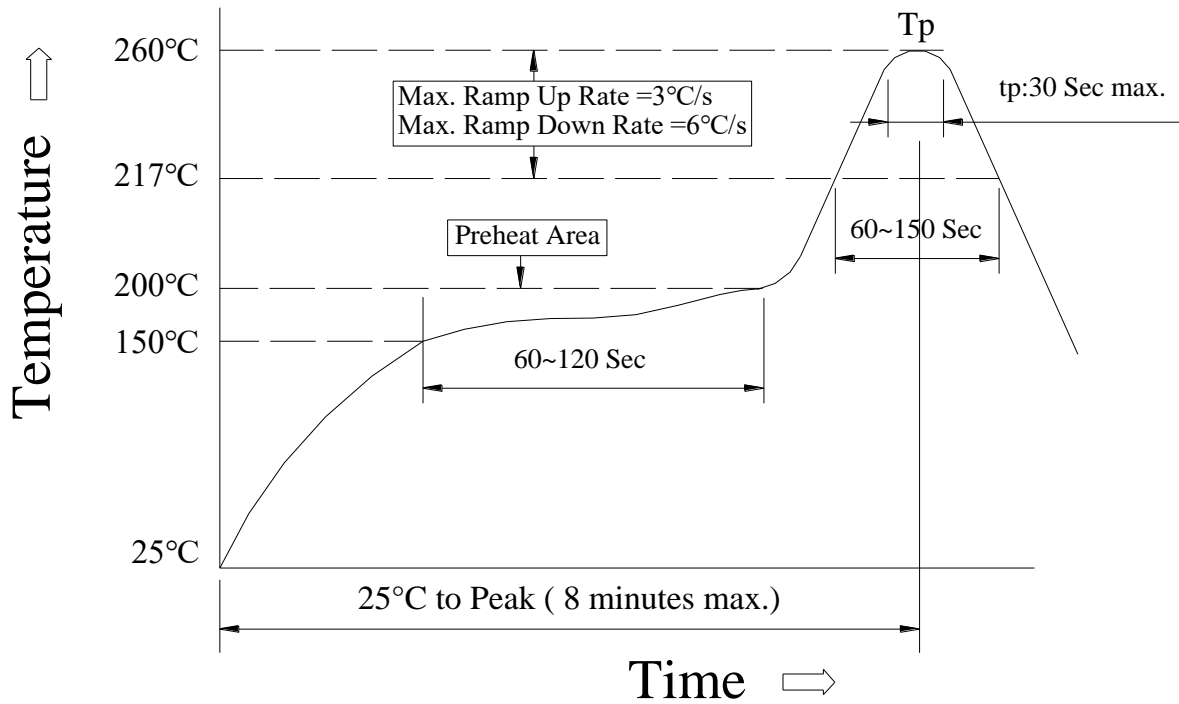
- (1) Chip resistor shall be stored in a room where temperature and humidity must be controlled.
(temperature 5 to 35°C, humidity < 60% RH) However, a humidity keep it low, as it is possible.
- (2) Chip resistor shall be stored as direct sunshine doesn't hit on it.
- (3) Chip resistor shall be stored with no moisture, dust, a material that will make solderability inferior, and a harmful gas (chloridation hydrogen, sulfurous acid gas, and sulfuration hydrogen).
- (4) Expiration date: One year after shipping date (product is required to return after expiration date)
- (5) Solderability should be confirmed in case of exceeding 12 months.

Care note for operating and handling

- (1) Protect the edge and coating of the sensors from mechanical stress.
- (2) Avoid bending of printing circuit board (PCB) when cutting and fixing it on support body to reduce mechanical stress on sensors.
- (3) Sensor should be used within the condition of specification.
Note: When a voltage higher than specified value is loaded to the sensor, this may damage the sensor material due to temperature rise.
- (4) The loaded voltage should consult terminal temperature of the sensor according to the derating curve.
- (5) When applying a high current exceeding suggested specification (pulse current, shock current) to the sensor, it is necessary to re-evaluate the operating condition before using it in the system.

Reflow profile :

Recommended Reflow Profile



(1) Reflow Soldering Method :

| | | |
|-------------------------------|----------------|-----------------------|
| Reflow Soldering | Tp:255~260°C | Max.30 seconds (tp) |
| | 217°C | 60~150 seconds |
| Pre-Heat | 150 ~ 200°C | 60~120 seconds |
| Time 25°C to peak temperature | 8 minutes max. | |

Reference : JEDEC J-STD-020E